

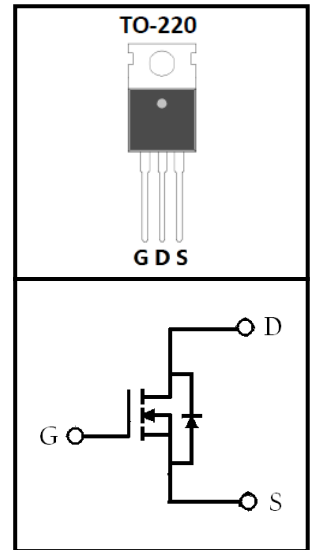
## 30V N-Channel Trench MOSFET

### FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits



### Device Marking and Package Information

Device	Package	Marking
CTP03N2P7	TO-220	CTP03N2P7

### Absolute Maximum Ratings at $T_j = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS} = 0\text{V}$ )	$V_{DSS}$	30	V
Continuous Drain Current $T_C = 25^\circ\text{C}$ (note1)	$I_D$	230	A
Continuous Drain Current $T_C = 100^\circ\text{C}$ (note1)		150	A
Pulsed Drain Current (note2)	$I_{DM}$	500	A
Gate Source Voltage	$V_{GSS}$	$\pm 20$	V
Single Pulse Avalanche Energy (note3)	$E_{AS}$	246	mJ
Power Dissipation $T_C = 25^\circ\text{C}$ (note4)	$P_D$	187	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+175	$^\circ\text{C}$

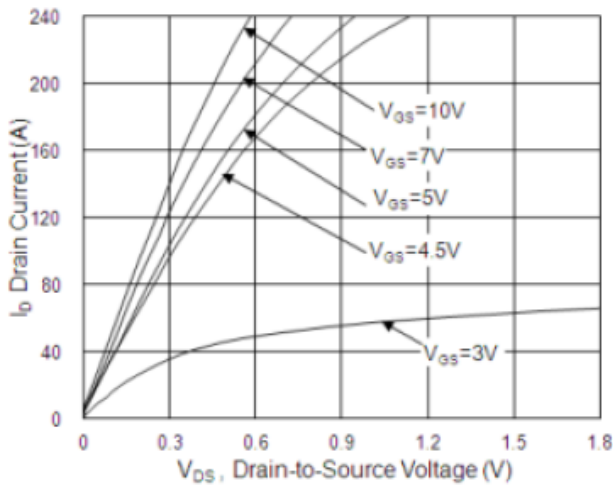
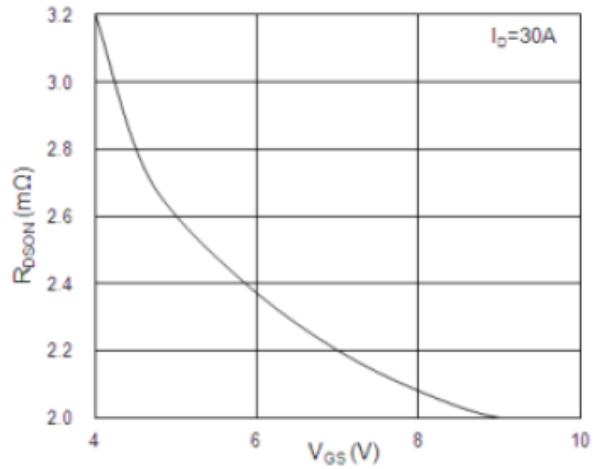
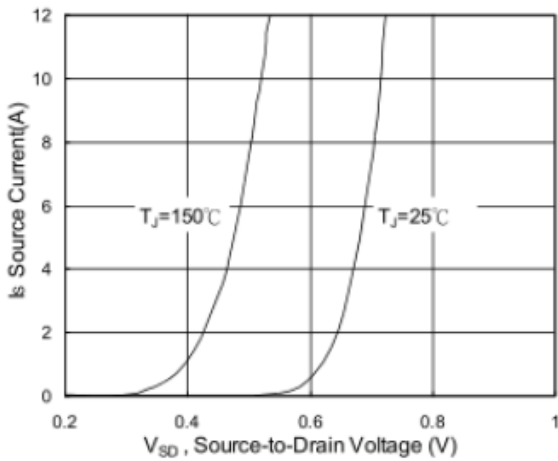
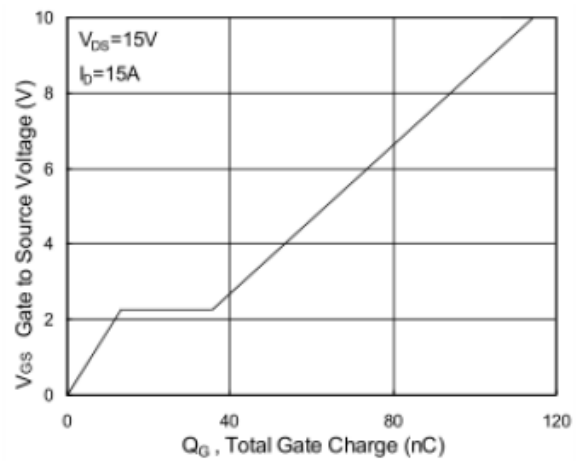
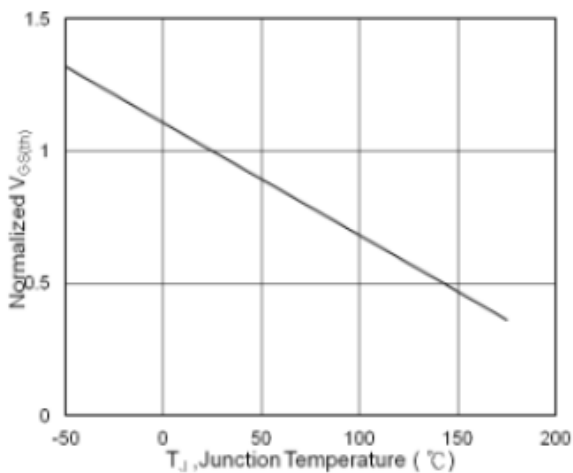
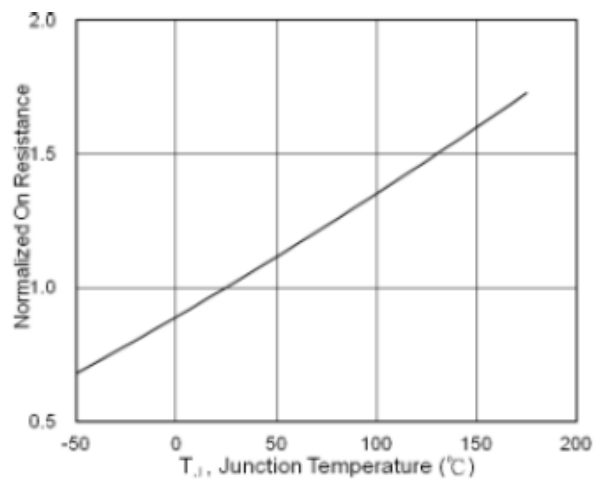
### Thermal Characteristics

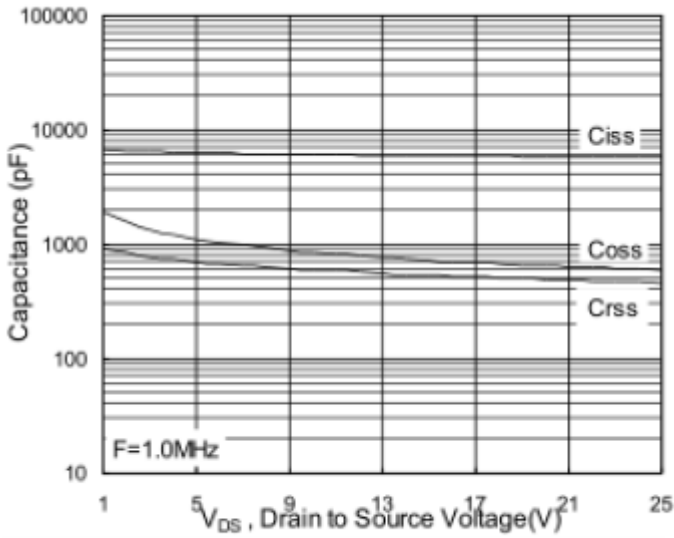
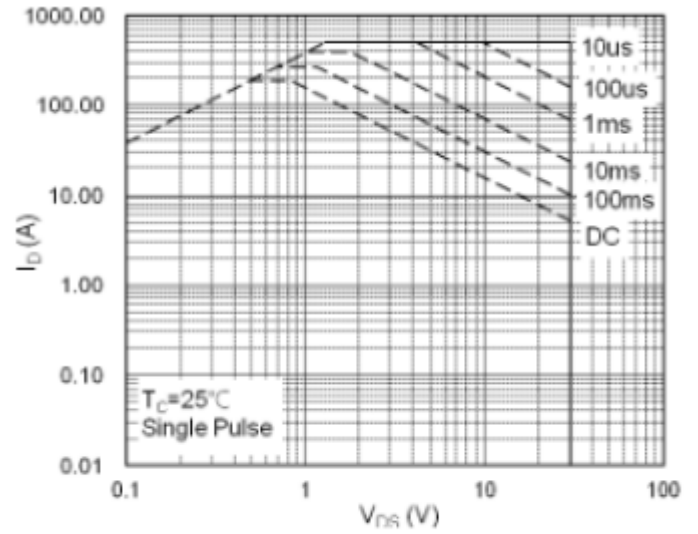
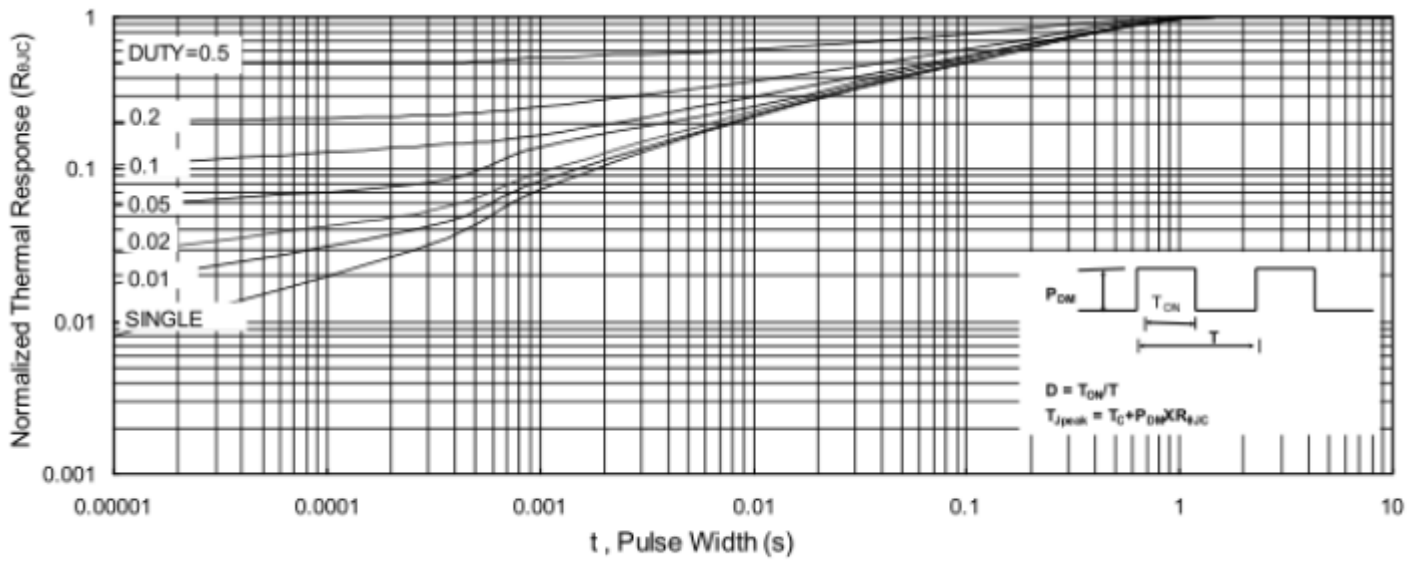
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.8	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (note1)	$R_{\theta JA}$	62	

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	$\mu A$
		$V_{DS} = 30V, V_{GS} = 0V, T_J = 55^\circ\text{C}$	--	--	5	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	--	2.5	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	--	2.0	2.7	m $\Omega$
		$V_{GS} = 4.5V, I_D = 15A$	--	2.6	3.8	m $\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 15V,$ $f = 1.0\text{MHz}$	--	5850	--	pF
Output Capacitance	$C_{oss}$		--	720	--	
Reverse Transfer Capacitance	$C_{rss}$		--	525	--	
Total Gate Charge (4.5V)	$Q_g$	$V_{DS} = 15V, I_D = 15A,$ $V_{GS} = 4.5V$	--	56.9	--	nC
Gate-Source Charge	$Q_{gs}$		--	13.8	--	
Gate-Drain Charge	$Q_{gd}$		--	23.5	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 15V, I_D = 1A$ $V_{GS} = 10V, R_G = 3\Omega$	--	20.1	--	ns
Turn-on Rise Time	$t_r$		--	6.3	--	
Turn-off Delay Time	$t_{d(off)}$		--	124.6	--	
Turn-off Fall Time	$t_f$		--	15.8	--	
<b>Body Diode Characteristics</b>						
Source-Drain Current(Body Diode)	$I_{SD}$		--	--	230	A
Pulsed Source-Drain Current(Body Diode)	$I_{SDM}$		--	--	500	
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 1A, V_{GS} = 0V$	--	--	1.2	V

**Notes**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$  , duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1\text{mH}$
4. The power dissipation is limited by 175 $^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs. G-S Voltage**

**Fig.3 Forward Characteristics of Reverse Diode**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

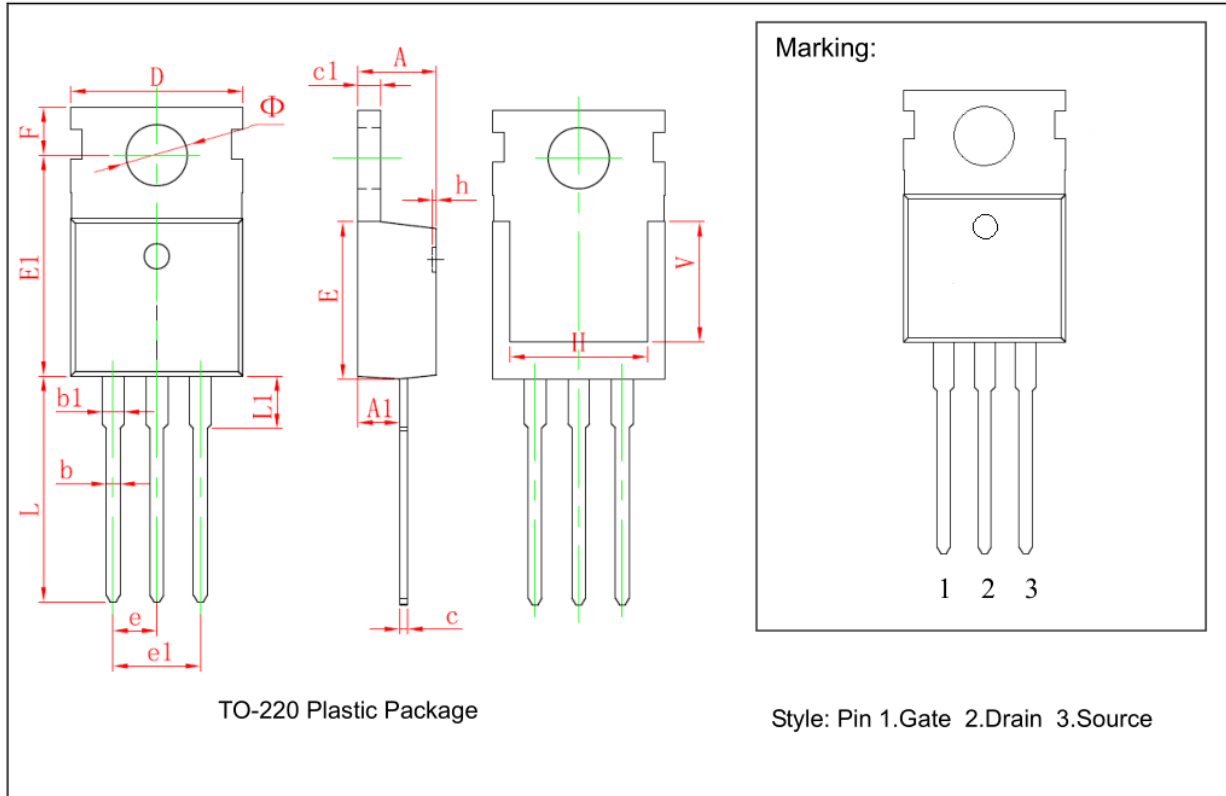
**Typical Characteristics**  $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**


## TO-220 Dimension



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181	e	2.540*		0.100*	
A1	2.250	2.550	0.089	0.100	e1	4.980	5.180	0.196	0.204
b	0.710	0.910	0.028	0.036	F	2.650	2.950	0.104	0.116
b1	1.170	1.370	0.046	0.054	H	7.900	8.100	0.311	0.319
c	0.330	0.650	0.013	0.026	h	0.000	0.300	0.000	0.012
c1	1.200	1.400	0.047	0.055	L	12.900	13.400	0.508	0.528
D	9.910	10.250	0.390	0.404	L1	2.850	3.250	0.112	0.128
E	8.950	9.750	0.352	0.384	V	7.500	REF	0.295	REF
E1	12.650	12.950	0.498	0.510	Φ	3.600	3.800	0.142	0.150

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